



NON RESIDUE SOLDER FLUX

MBO "UNIFLUX LSi"

"UNIFLUX™ LSi" is specifically manufactured to leave no remaining residue after soldering to eliminate the need for circuit cleaning and effectively saving the relative costs.

Dirt accumulation in machines and on circuit board carriers is significantly reduced.

Soldering efficiency is equal to that of resinous flux, type RMA.

Halide free, it leaves no corrosive elements after processing.

"UNIFLUX™ LSi" is manufactured to conform with French Standards NFC 90550 and international standards J-STD 004.

Physiochemical Characteristics:

Solution	: Alcoholised
Coloration	: Straw
Density at 25°C	: 0.838 g/cm ³
Non volatile content	: < 6 %
Chlorine rate	: Halide free
Corrosiveness	: None.
Flash point	: 12°C
Acid index	: 29 +/- 0.8 mgKOH/g
Insulation resistance	: > 100 GΩ

Application Notes:

MBO UNIFLUX™ LSi was especially developed for dipping soldering processes. However, it can also be used in other processes such as spray, wave or foam fluxing systems as are available in many standard types of soldering equipment.

Pre-heating temperature should be between 80°C and 120°C.

Because of the inherent high resistance to temperature, the flux can be used in hot-deep soldering baths for enamelled wires for tinning purposes. The dipping solder bath temperature may be adjusted up to 480 C if required. For wave soldering applications normal operating temperatures of around 250 C are also acceptable.

Carry out regular checks of the density or acidity index and maintain the recommended level by adding dilutant, if required.

Health and Safety:

As with all soldering flux, MBO Uniflux LSi must be used in a well ventilated area away from any source of flame or ignition (COSH sheet available).

Packaging:

Throwaway plastic containers containing 10 litres.

Store in original hermetically sealed containers, stored at an ideal temperature near 20°C for 12 months maximum.